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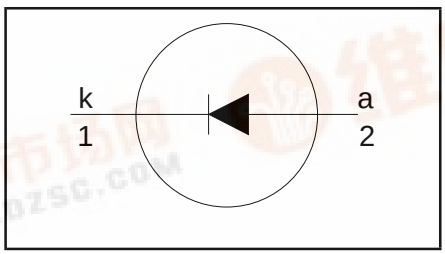
Rectifier diodes Schottky barrier

PBYR10100X series

FEATURES

- Low forward volt drop
- Fast switching
- Reverse surge capability
- High thermal cycling performance
- Isolated mounting tab

SYMBOL



QUICK REFERENCE DATA

V_R = 100 V

$I_{F(AV)}$ = 10 A

$V_F \leq 0.74$ V

GENERAL DESCRIPTION

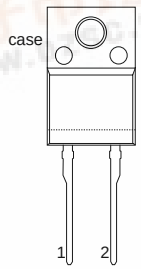
Schottky rectifier diodes in a plastic envelope with electrically isolated mounting tab. Intended for use as output rectifiers in low voltage, high frequency switched mode power supplies.

The PBYR10100 series is supplied in the conventional leaded SOD113 package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode
case	isolated

SOD113 (SOT186A)



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	Peak repetitive reverse voltage		-	100	V
V_{RWM}	Working peak reverse voltage		-	100	V
V_R	Continuous reverse voltage	$T_{hs} \leq 115$ ˚C	-	100	V
$I_{F(AV)}$	Average rectified forward current	square wave; $\delta = 0.5$; $T_{hs} \leq 114$ ˚C	-	10	A
I_{FRM}	Repetitive peak forward current	square wave; $\delta = 0.5$; $T_{hs} \leq 114$ ˚C	-	20	A
I_{FSM}	Non-repetitive peak forward current	t = 10 ms	-	135	A
		t = 8.3 ms	-	150	A
		sinusoidal; T_j = 125 ˚C prior to surge; with reapplied $V_{RRM(max)}$			
I_{RRM}	Peak repetitive reverse surge current	pulse width and repetition rate limited by $T_{j\,max}$	-	1	A
T_j	Operating junction temperature		-	150	˚C
T_{stg}	Storage temperature		- 65	150	˚C

ISOLATION LIMITING VALUE & CHARACTERISTIC

T_{hs} = 25 ˚C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{isol}	R.M.S. isolation voltage from both terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65% ; clean and dustfree	-		2500	V
C_{isol}	Capacitance from both terminals to external heatsink	f = 1 MHz	-	10	-	pF

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j\text{-}hs}$	Thermal resistance junction to heat sink		-	-	4	K/W
$R_{th\ j\text{-}a}$	Thermal resistance junction to ambient	in free air	-	55	-	K/W

ELECTRICAL CHARACTERISTICS

T_j = 25 ˚C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	Forward voltage	I_F = 10 A; T_j = 125˚C	-	0.64	0.74	V
		I_F = 20 A; T_j = 125˚C	-	0.79	0.90	V
		I_F = 20 A	-	0.94	1.00	V
I_R	Reverse current	$V_R = V_{RWM}$	-	5	150	µA
		$V_R = V_{RWM}$; T_j = 125˚C	-	5	15	mA
C_d	Junction capacitance	V_R = 5 V; f = 1 MHz, T_j = 25˚C to 125˚C	-	420	-	pF

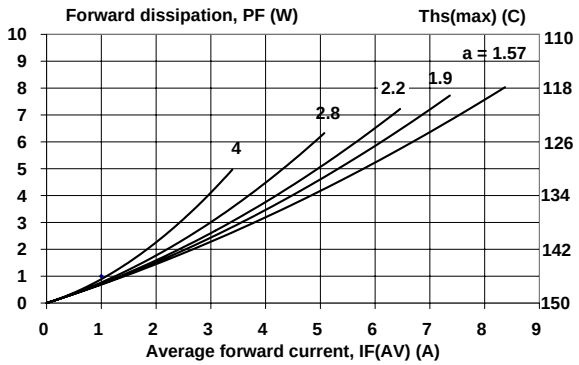

Fig.1. Maximum forward dissipation $P_F = f(I_{F(AV)})$; square current waveform where $I_{F(AV)} = I_{F(RMS)} \times \sqrt{D}$.

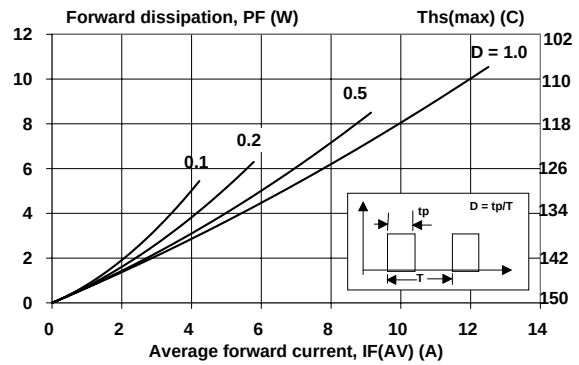

Fig.2. Maximum forward dissipation $P_F = f(I_{F(AV)})$; sinusoidal current waveform where a = form factor = $I_{F(RMS)} / I_{F(AV)}$.

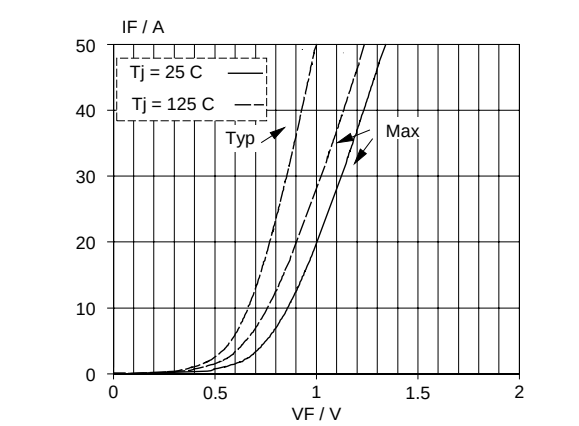

Fig.3. Typical and maximum forward characteristic $I_F = f(V_F)$; parameter T_j

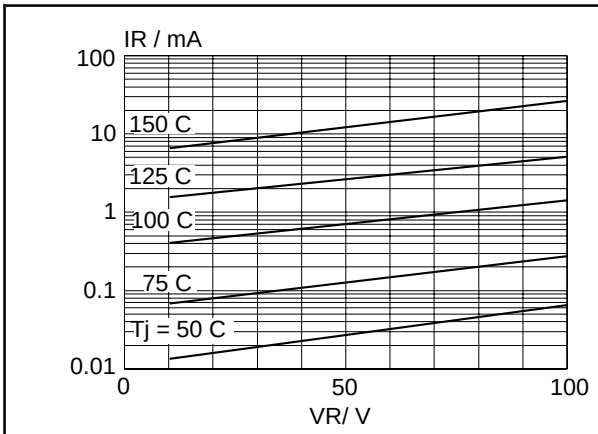

Fig.4. Typical reverse leakage current; $I_R = f(V_R)$; parameter T_j

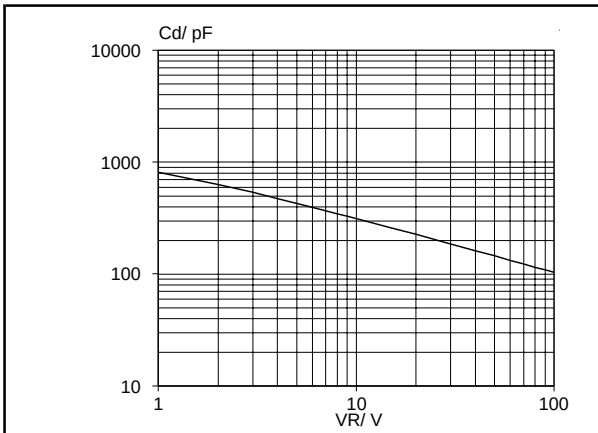

Fig.5. Typical junction capacitance; $C_d = f(V_R)$; f = 1 MHz; T_j = 25˚C to 125 ˚C.

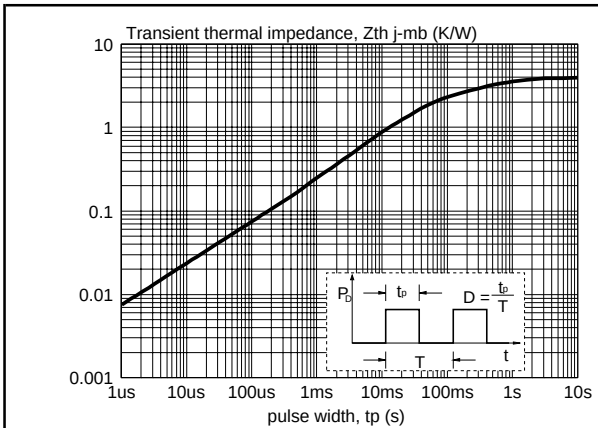

Fig.6. Transient thermal impedance; $Z_{th\ j\text{-}mb} = f(t_p)$.

MECHANICAL DATA

Dimensions in mm

Net Mass: 2 g

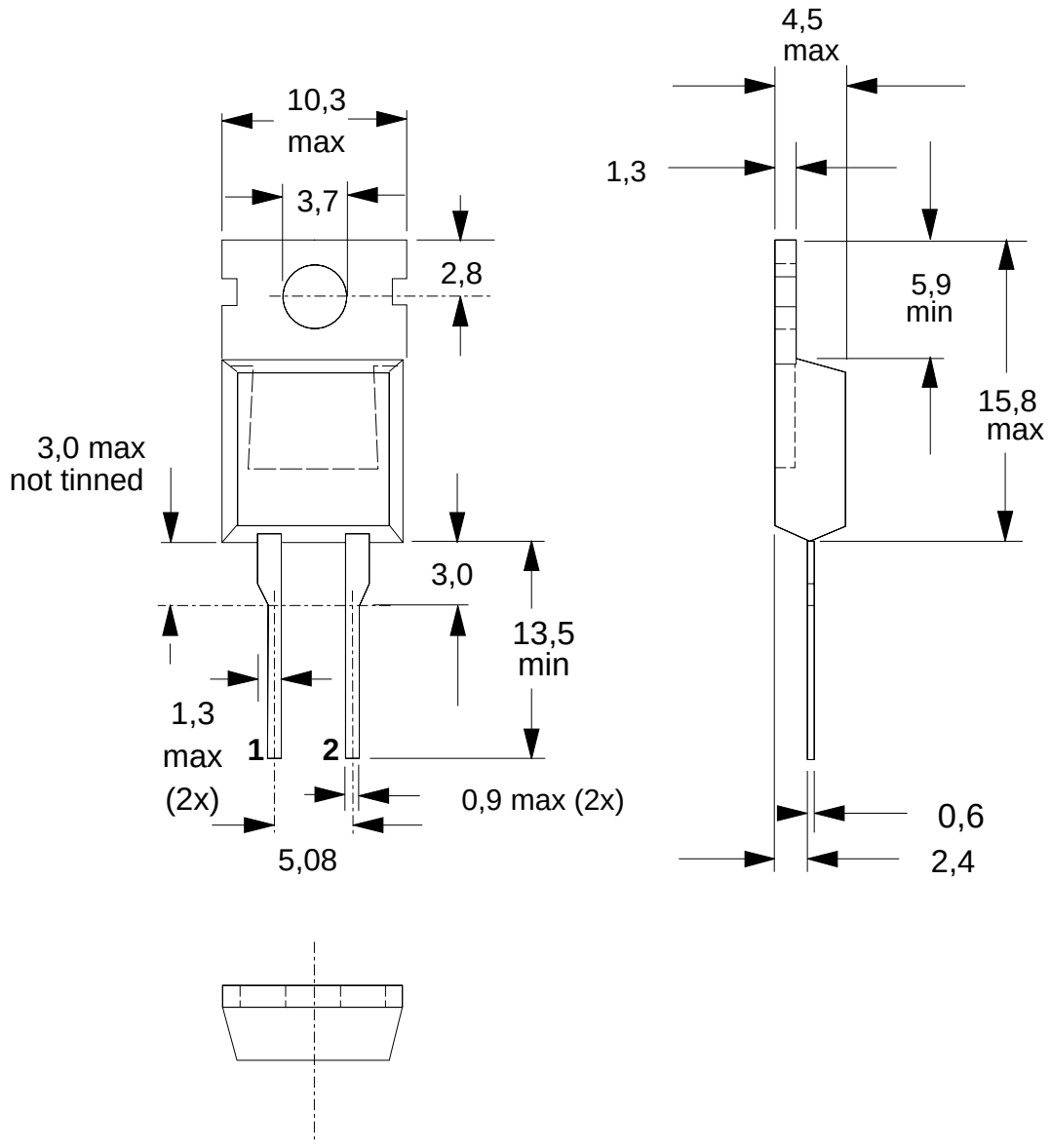

Fig.7. SOD59 (TO220AC). pin 1 connected to mounting base.

Notes
1. Refer to mounting instructions for TO220 envelopes.
2. Epoxy meets UL94 V0 at 1/8".

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

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